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(71) Applicant *(for all designated States except US)*: **NXP B.V.** [NL/NL]; High Tech Campus 60, NL-5656 AG Eindhoven (NL).

(72) Inventors; and

(75) Inventors/Applicants *(for US only)*: **SCHRAVENDEEL, Ronald** [NL/NL]; c/o NXP Semiconductors Austria GmbH, Intellectual Property Department, Gutheil-Schoder-Gasse 8-12, A-1102 Vienna (AT).

SCHELWALD, Peter [NL/NL]; c/o NXP Semiconductors Austria GmbH, Intellectual Property Department, Gutheil-Schoder-Gasse 8-12, A-1102 Vienna (AT).

(74) Agent: **VAN DER VEER, Johannis, Leendert**; NXP Semiconductors, IP & L Department, High Tech Campus 32, NL-5656 AE Eindhoven (NL).

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(54) Title: A LEADFRAME STRUCTURE FOR ELECTRONIC PACKAGES

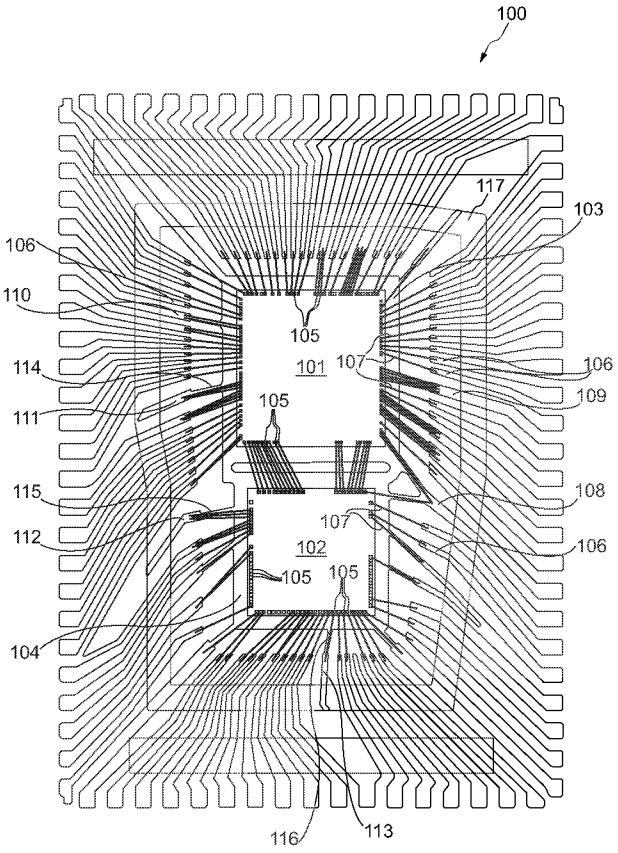


Fig. 1

(57) Abstract: A leadframe structure (100) for an electronic package is provided, wherein the leadframe structure (100) comprises a die-pad (103), a barrier area (114), and a bonding area (111), wherein the barrier area (114) is arranged between the die-pad (103) and the bonding area (111), and wherein the barrier area (111) is adapted to electrically connect the die-pad (103) and the bonding area (111), and is further constructed in such a way that delamination growth between the leadframe structure (100) and a moulding compound fixable to the leadframe structure (100) is reduced.

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B. FIELDS SEARCHED

Minimum documentation searched (classification system followed by classification symbols)
H01L

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched

Electronic data base consulted during the international search (name of data base and, where practical, search terms used)
EPO-Internal, WPI Data

C. DOCUMENTS CONSIDERED TO BE RELEVANT

Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
P,X	US 2007/212903 A1 (PUNZALAN JEFFREY D [SG] ET AL) 13 September 2007 (2007-09-13) paragraphs [0040], [0044], [0049]; figure 4	1-7
X	JP 07 045778 A (SUMITOMO ELECTRIC INDUSTRIES) 14 February 1995 (1995-02-14) abstract; figures 1-4	1,3-7
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X	US 2004/061204 A1 (HAN BYUNG JOON [SG] ET AL) 1 April 2004 (2004-04-01) paragraph [0042]; figure 3	1,2,5-7

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[X] See patent family annex.

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Name and mailing address of the ISA/	Authorized officer
European Patent Office, P.B. 5818 Patentlaan 2 NL – 2280 HV Rijswijk Tel. (+31-70) 340-2040, Fax: (+31-70) 340-3016	Zeisler, Peter

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C(Continuation). DOCUMENTS CONSIDERED TO BE RELEVANT

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Information on patent family members

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